

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MING-CHIN CHIEN	06/04/2014
JUI-CHING WU	06/04/2014
SHU-HAO CHANG	06/04/2014
SHANG-CHIEH CHIEN	06/04/2014
JEN-YANG CHUNG	06/04/2014
KUO-CHANG KAU	06/04/2014
JENG-HORNG CHENG	06/04/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14280182
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	2013-1886 - 24061.2777
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/

PATENT

DATE SIGNED:	08/08/2014
Total Attachments: 3 source=24061.2777 - 2013-1886 - Response Informational Notice Applicant Filed 08-08-2014#page12.tif source=24061.2777 - 2013-1886 - Response Informational Notice Applicant Filed 08-08-2014#page13.tif source=24061.2777 - 2013-1886 - Response Informational Notice Applicant Filed 08-08-2014#page14.tif	

Docket No.: 2013-1886 /24061.2777
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-------------------|----|---|
| (1) | Ming-Chin Chien | of | No. 52, Jinshan E. 3rd Street, East District
Hsinchu City 300, Taiwan, R.O.C. |
| (2) | Jui-Ching Wu | of | 10F., No. 223, Bade Road, East District
Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Shu-Hao Chang | of | 3F., No. 229, Raohe Street, Songshan District
Taipei City 105, Taiwan, R.O.C. |
| (4) | Shang-Chieh Chien | of | 2F., No. 8, Lane 113, Section 3, Sanhe Road
Sanchong District, New Taipei City 241
Taiwan, R.O.C. |
| (5) | Jen-Yang Chung | of | No. 8, Li-Hsin Road. 6
Science-Based Industrial Park
Hsin-Chu 300-77, Taiwan, R.O.C. |
| (6) | Kuo-Chang Kau | of | No. 52, Beifang, Yuanli Township
Miaoli County 358, Taiwan, R.O.C. |
| (7) | Jeng-Horng Chen | of | 1, Alley 2, Lane 45, Fu-Chyun Street
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

SEMICONDUCTOR INTEGRATED CIRCUIT FABRICATION WITH PATTERN-REVERSING PROCESS

for which we have filed an application for Letters Patent of the United States of America on May 16, 2014, as U.S. Serial No. 14/280,182; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said

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invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ming-Chin Chien

Residence Address: No. 52, Jinshan E. 3rd Street, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 6/4

簡 昌 進 Ming-Chin Chien
Inventor Signature

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Dated: 6/4, 2014

Jui-Ching Wu
Inventor Signature

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Dated: 6/4 2014

Shu-Hao Chang
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Dated: 6.4. 2014.

Shang-Chieh Chien.
Inventor Signature

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Dated: 6/4 2014

Jen-Yang Chung
Inventor Signature

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Residence Address: No. 52, Beifang, Yuanli Township, Miaoli County 358, Taiwan, R.O.C.

Dated: Kuo-Chang Kau. 6/4 2014.

Kuo-Chang Kau.
Inventor Signature

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Dated: 6/4 2014

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